

# **HZU6.2Z**

# Silicon Epitaxial Planar Zener Diode for Surge Absorb

REJ03G1218-0200

(Previous: ADE-208-581A)

Rev.2.00 Jun 16, 2005

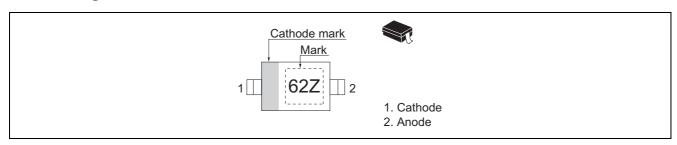
### **Features**

- Low capacitance (C = 8.5 pF max) and can protect signal line from ESD.
- Ultra small Resin Package (URP) is suitable for surface mount design.

## **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZU6.2Z	62Z	URP	PTSP0002ZA-A (URP)

## **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

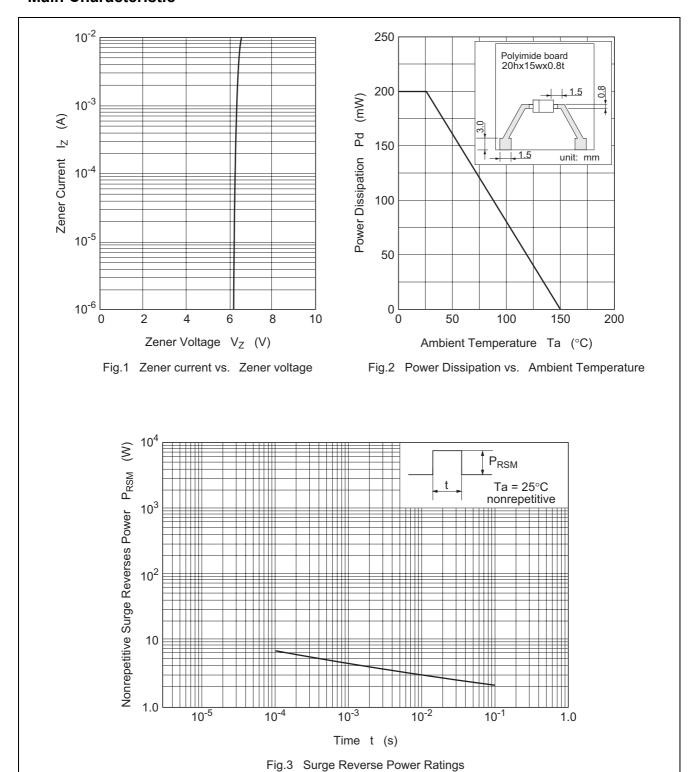
Note: See Fig.2.

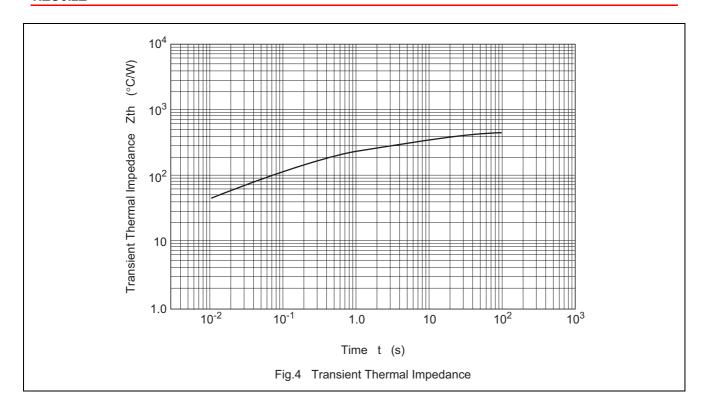
## **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

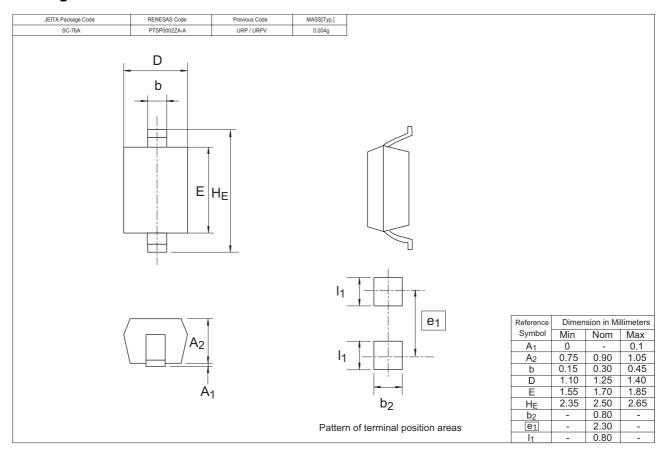
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	5.90		6.50	>	$I_Z = 5$ mA, 40 ms pulse
Reverse current	I <sub>R</sub>	_	_	3	μΑ	V <sub>R</sub> = 5.5 V
Capacitance	С	_	8.0	8.5	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Dynamic resistance	r <sub>d</sub>			60	Ω	$I_Z = 5 \text{ mA}$

### **Main Characteristic**





## **Package Dimensions**



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